



Material Content Data Sheet



Sales Product Name		BAS 70-06 E6327		Issued		29. August 2013		
MA#		MA000504282						
Package		PG-SOT23-3-11		Weight*		8.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.006	0.07		680	
	inorganic material	silicon	7440-21-3	0.051	0.58	0.65	5816	6496
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		925	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		308	
wire	non noble metal	copper	7440-50-8	2.704	30.71	30.84	307139	308434
	noble metal	gold	7440-57-5	0.011	0.13	0.13	1301	1301
	organic material	carbon black	1333-86-4	0.058	0.66		6556	
	plastics	brominated resin	-	0.087	0.98		9835	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.115	1.31		13113	
	plastics	epoxy resin	-	1.241	14.10		140961	
	inorganic material	silicondioxide	60676-86-0	4.272	48.52	65.57	485169	655634
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16996	16996
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11139	11139
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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